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# CMOS Photonics 101

Contributors:

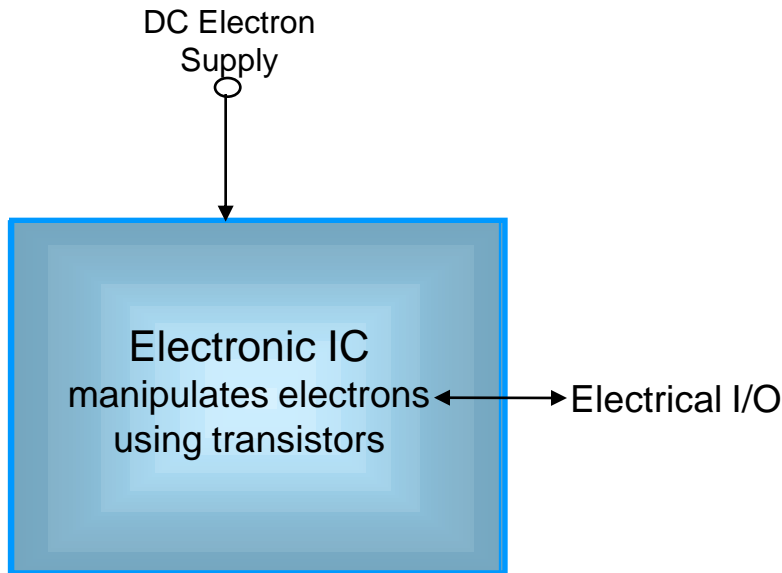
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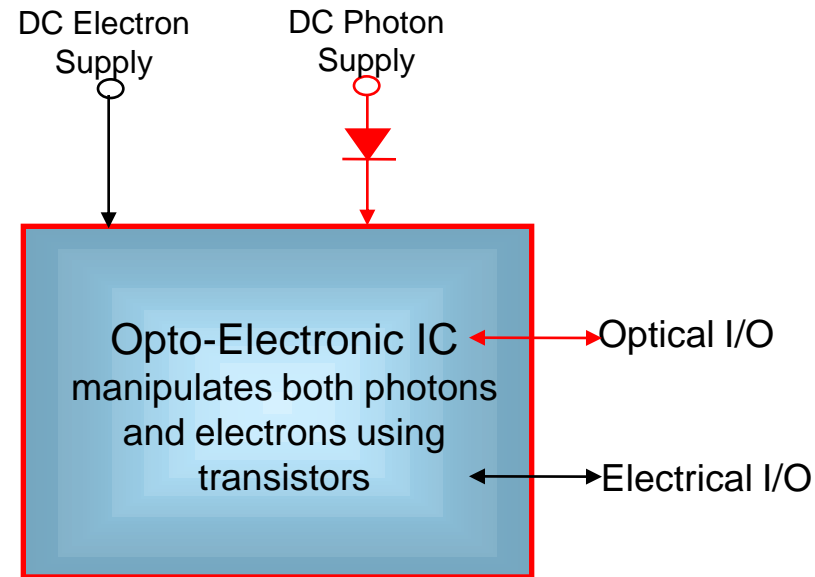
# What is CMOS Photonics?

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## CMOS IC Platform



## CMOS Photonics IC Platform

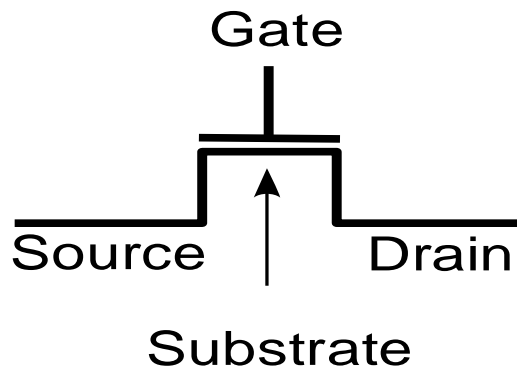


*CMOS Photonics IC Platform leverages existing multi-billion dollars of investment, Infra-structure and discipline of the CMOS IC industry to manipulate both Electrons & Photons to achieve desired Opto-Electronics functions using External DC Sources*

# Fundamental Technology

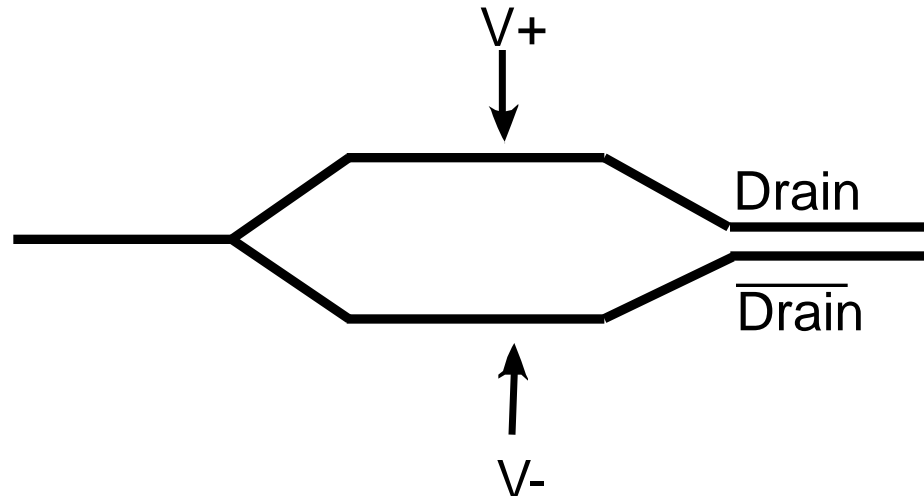
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## MOS Transistor



By controlling the voltages on terminals, MOS Transistor controls the flow of electrons from source to drain. Today, 100s of millions can be placed on a single electronics chip.

## CMOS Photonics Modulator



By controlling the voltages of the two arms of the modulator, one controls the flow of photons from source to drain with one major difference – Photons cannot be stopped and hence the unwanted will go to Drain. A large numbers of these can be integrated on a single chip.

**Just like the transistor is the basic building block for all ICs, Broadband Modulator is the basic building block for all high speed optical interconnects**

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# Optical Components and Libraries in CMOS

## Silicon waveguides:

- SOI and etched trenches for respectively vertical and horizontal elements
- Small mode size -> small bending radii -> compact photonic components
- Demonstrated losses < 0.1 dB/cm

## Library of passive waveguide structures

- Termination
- Splitters
- Directional couplers

## Library of fiber-to-the-chip couplers

- Single and polarization splitting grating couplers
- Low loss-coupling waveguide to single mode fiber
- Enable wafer scale optical testability

## Library of waveguide photo-detectors

- Selective epitaxy of germanium on silicon
- Enable low cost, high-sensitivity integrated receivers

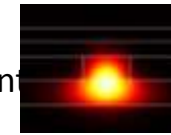
## Library of phase modulators

- Building block for intensity modulators (MZI, ring,...)
- Very high modulation bandwidth: ~ 160 GHz

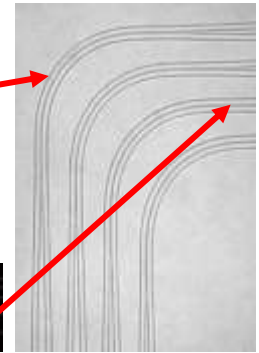
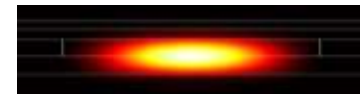
Cross-section single mode waveguide



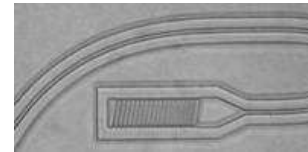
Single Mode



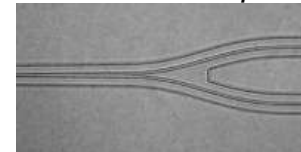
Multi Mode



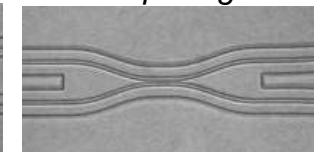
Waveguide Termination



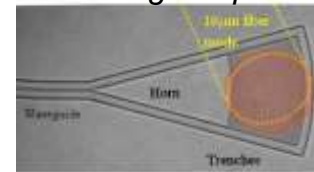
Y-junction



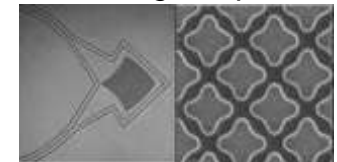
Directional Coupler: Low loss 50% splitter tunable splitting ratio



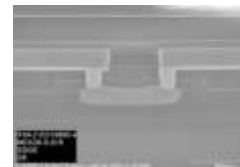
Single Polarization Grating Coupler



Polarization Splitting Grating Coupler



Germanium Detector



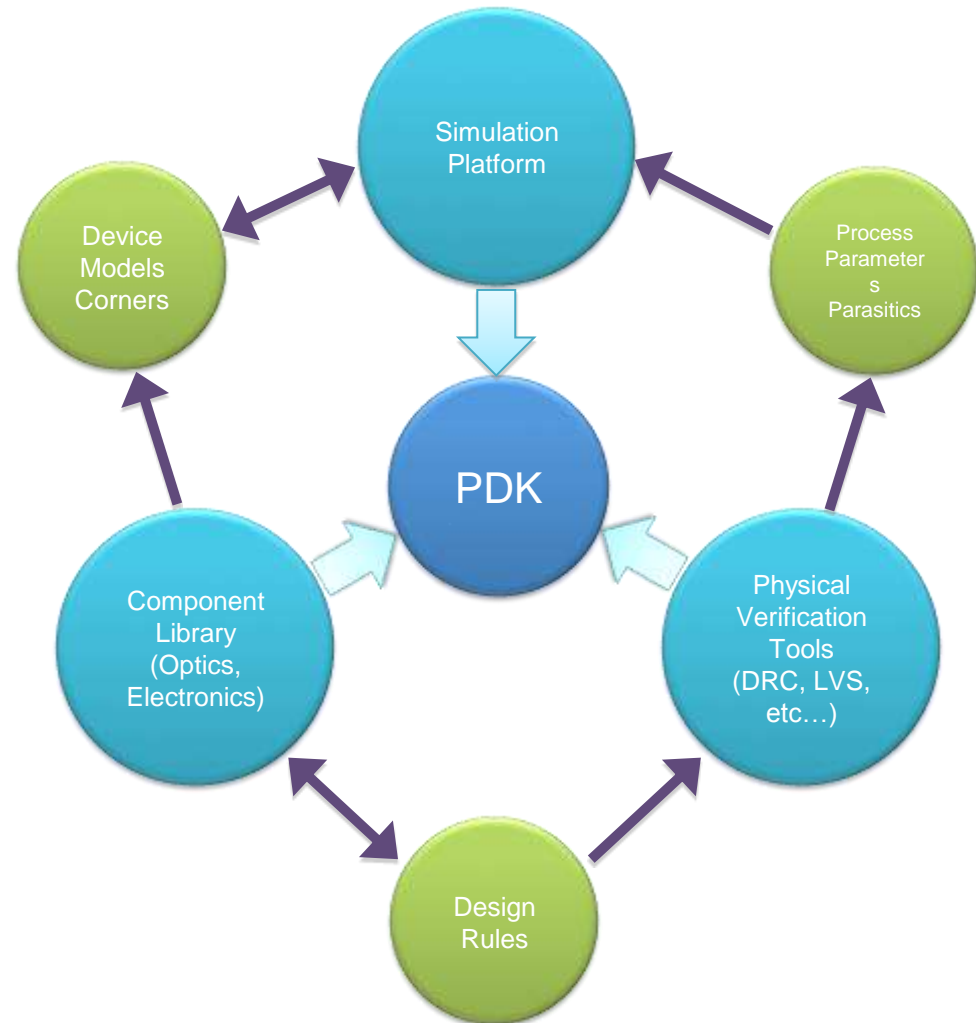
Integrated Receiver



# Design Tools: Process Design Kit (PDK)

## ENABLE ELECTRONICS TYPE OF DESIGN PROCESSES FOR OPTICS

- Basic set of optical design rules
  - Process checks
  - Device checks
  - Interaction of optics and electronics
  - Run separately from electrical DRC
- LVS
  - Additional optical LVS for optical connectivity
  - Additional OE LVS for devices connecting to electrical circuits
- Simulation
  - OE simulation of complete subsystems
  - Using electrical models to represent subset of optical devices





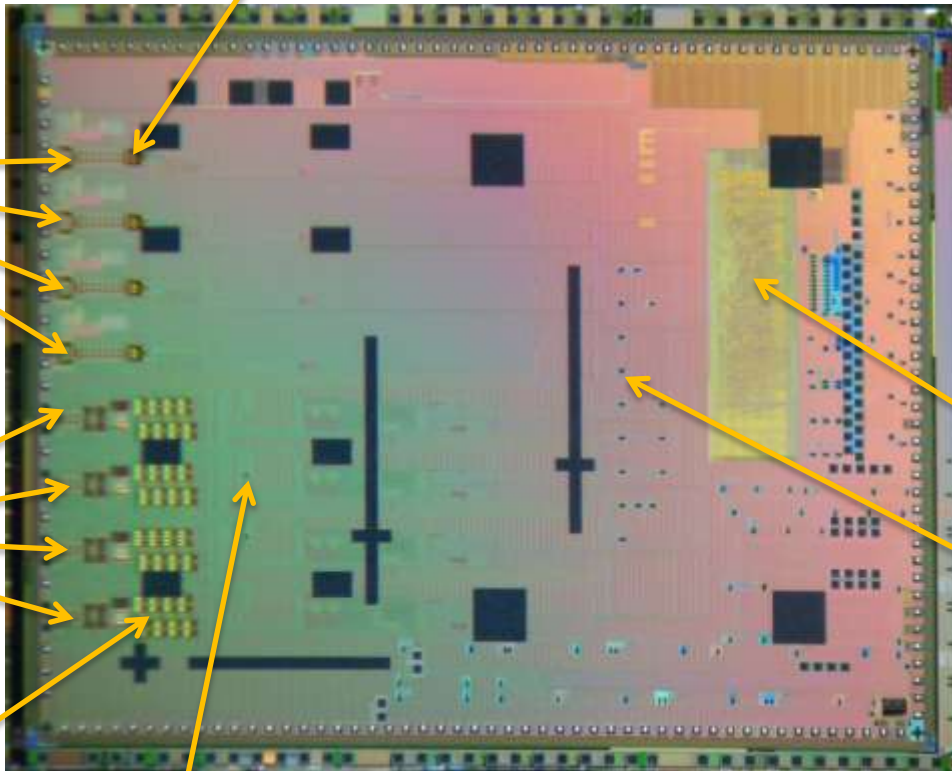


# Single Chip 4x28Gbps Optical Transceiver

Receiver / Photo-Detector

RXs

TXs



Digital core

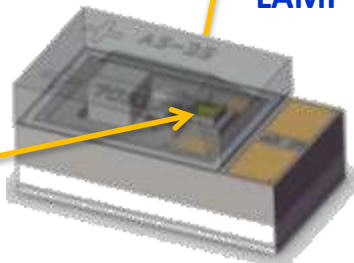
8 Fiber array I/Os

4 for transmit and 4 for receive

Transmitter / Modulator

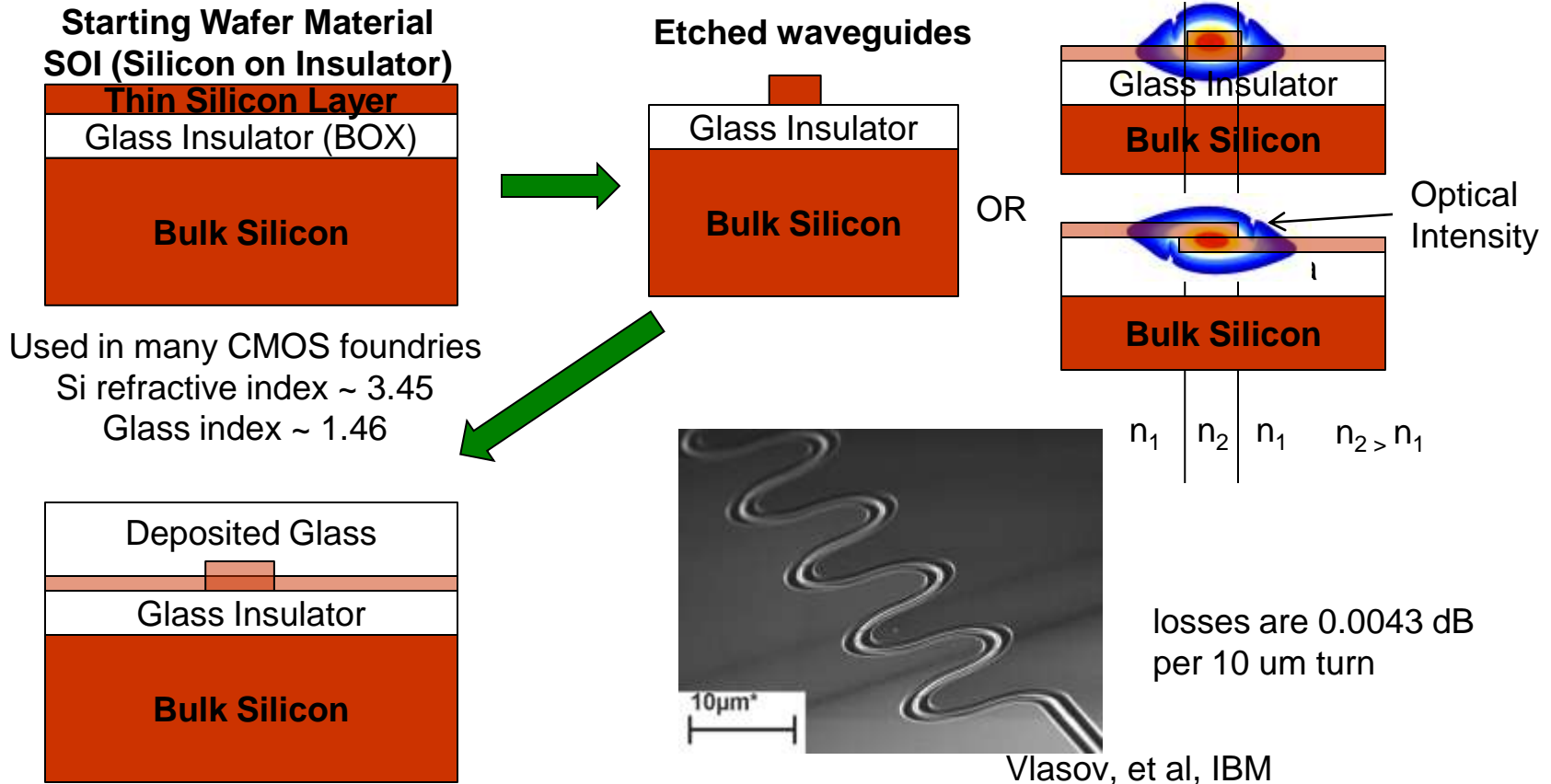
LAMP Packaged Light Source

Single CW Laser  
Split 4 ways



- Die size (5 mm x 6 mm)
- Die size is driven by laser and fiber attachment
- White space available for additional logic

# Waveguides & Refractive Index in CMOS

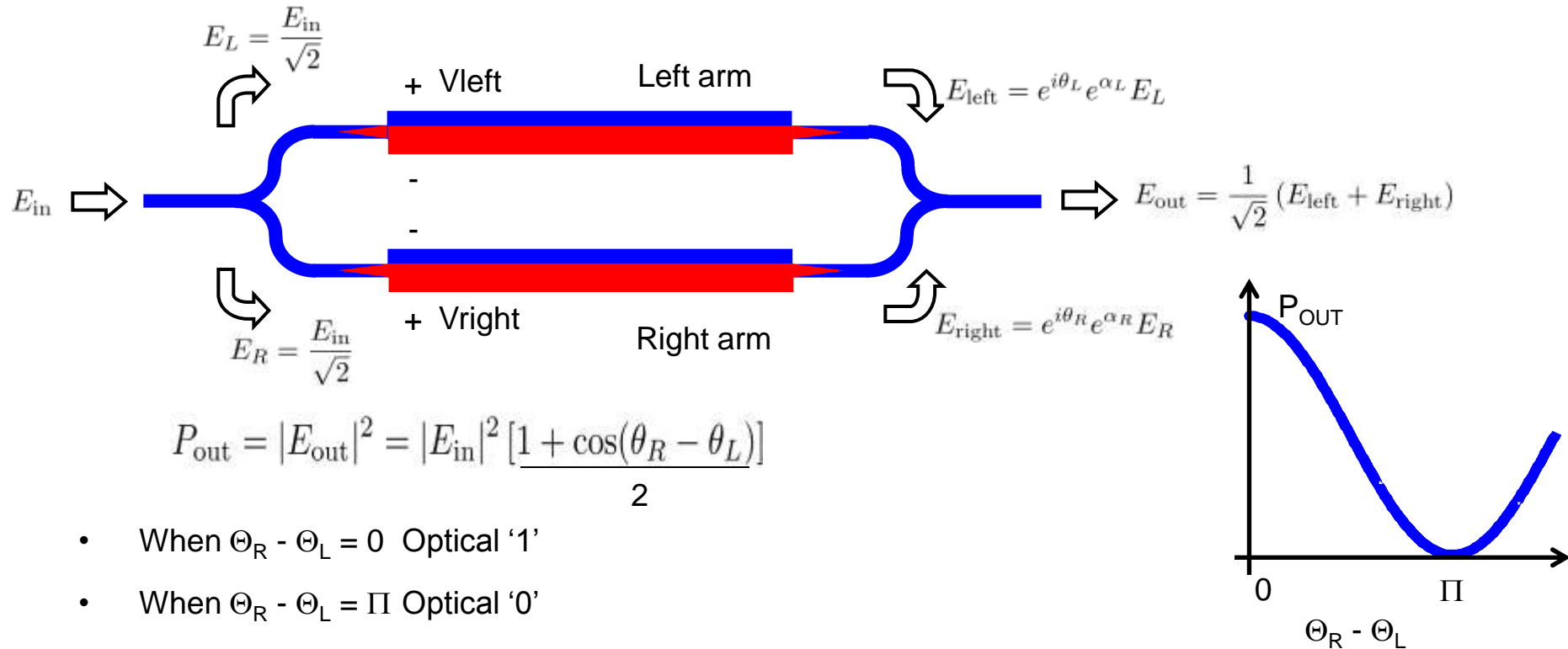


- Optically smooth surfaces are now possible in mature CMOS processes
- CMOS photonics uses standard CMOS equipment and processes
- Silicon is transparent at  $\lambda > 1.1 \mu\text{m}$
- High index contrast waveguide enables micron size devices



# Mach Zehnder Interferometer (MZI)

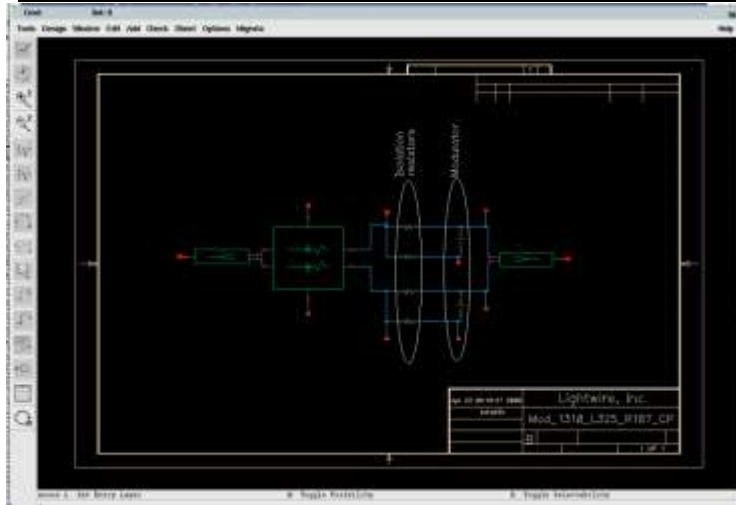
## Modulator overview



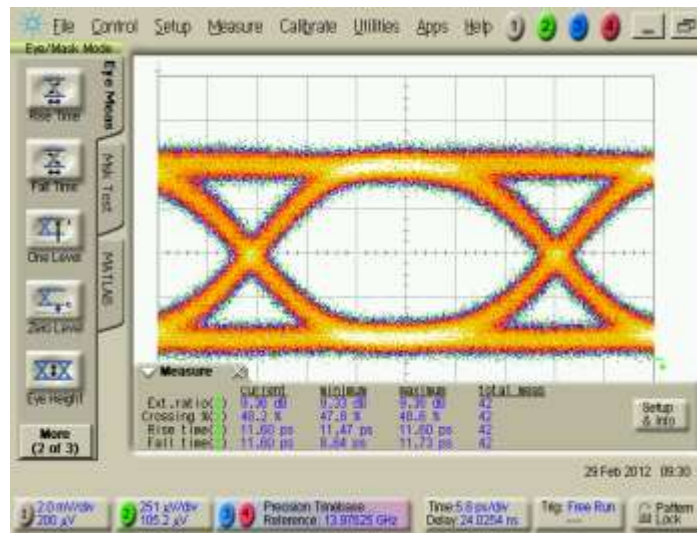
- When  $\theta_R - \theta_L = 0$  Optical '1'
- When  $\theta_R - \theta_L = \Pi$  Optical '0'
- Applying a + / - voltage on Vright decreases / increases  $\theta_R$  respectively.
- Applying a + / - voltage on Vleft decreases / increases  $\theta_L$  respectively.
- For silicon modulators, the applied + / - voltage injects / removes electrons and holes in the optical path which changes the optical index => Free Carrier Plasma Dispersion Effect

MZI deployed in optical systems for over 20 years

# Tx Optical Eyes at 28Gbps – Simulation and Measurement:



Cadence MZI Simulation Model



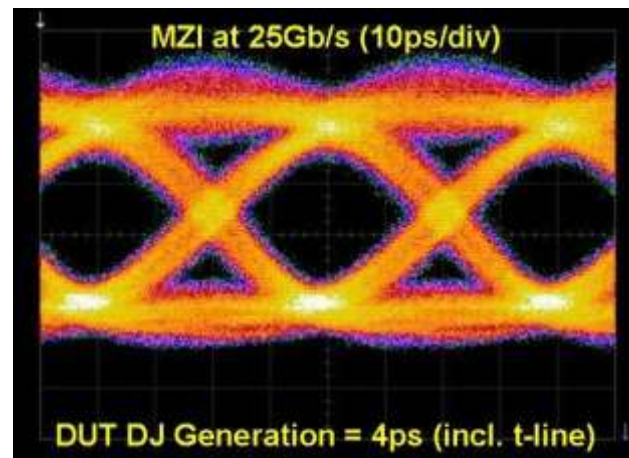
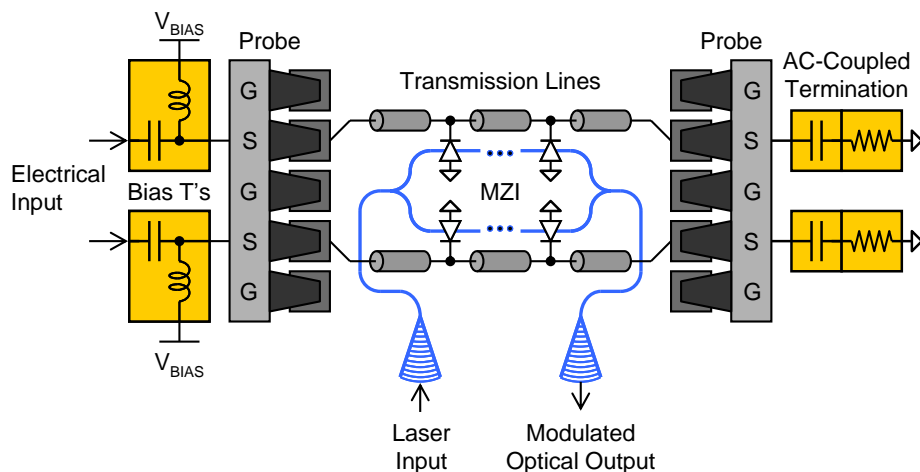
- 28G optical eye
- PRBS-31
- ER = 9.3 dB
- Trise/Tfall ~ 12ps (20%-80%)

Simulation

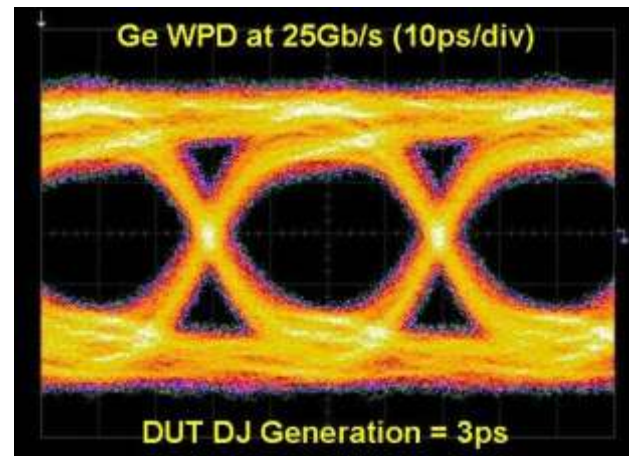
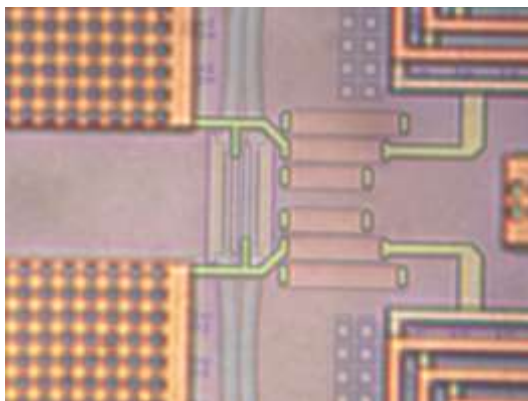
**Excellent correlation between simulation and measurement**

# Demonstrated 25G Performance

## 25G Modulator Demonstrated in Silicon



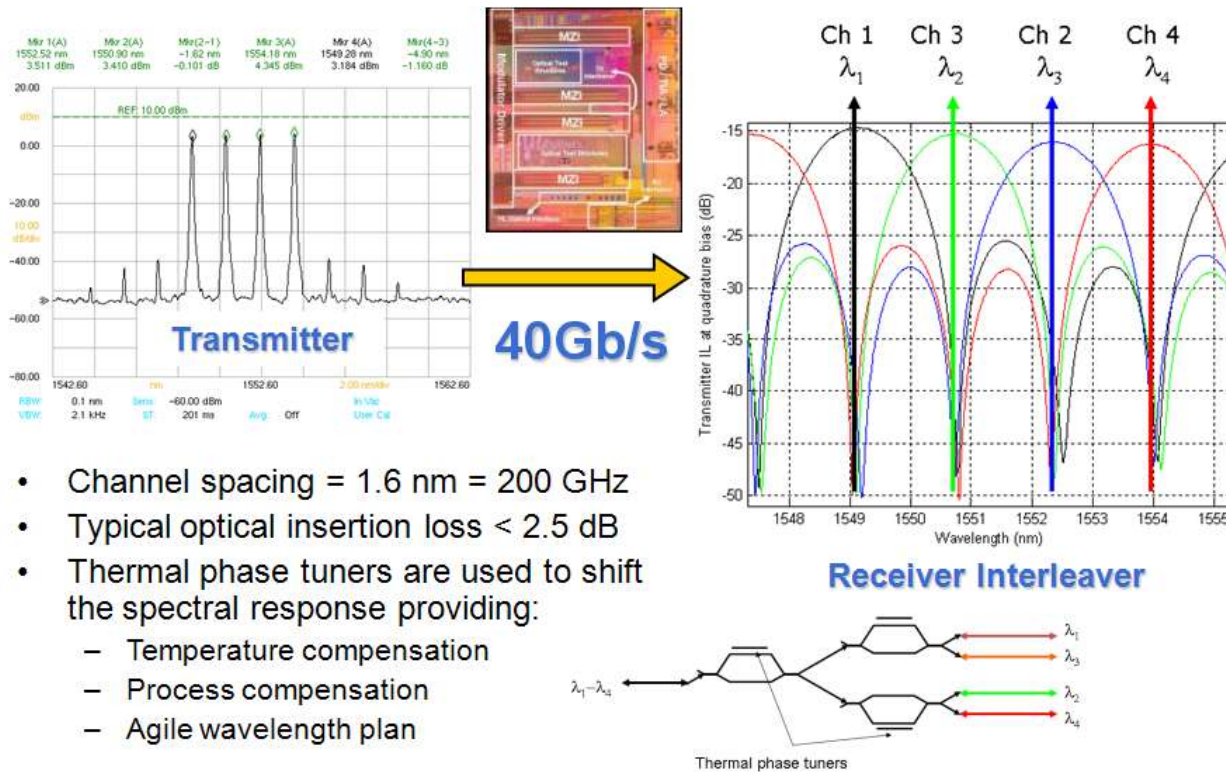
## 25G Photodetector Demonstrated in Silicon



# Technology Roadmap - Fiber Capacity

**CMOS Photonics enables several ways to increase channel capacity beyond raw data rate:**

- Wavelength diversity (WDM): Enabled by on-chip MUX/DEMUX.
- Multi-level signaling (i.e. PAM-4): Simplified by external laser modulation



- Channel spacing = 1.6 nm = 200 GHz
- Typical optical insertion loss < 2.5 dB
- Thermal phase tuners are used to shift the spectral response providing:
  - Temperature compensation
  - Process compensation
  - Agile wavelength plan

# CMOS Photonics Integration - Advantages

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- Low power
  - 780mw for 4x10G QSFP today (20mW/Gbit)
- Enables high density solutions
  - CMOS Photonics Physical Density > 130 Gbps/mm<sup>2</sup>
  - CMOS Photonics I/O Density > 400 Tbps/mm<sup>2</sup>
  - Show CFP going to SFP



# CMOS Photonics

## Summary of Capabilities

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- Performance
  - Reliable (1M ports shipped to date)
  - Extremely small devices due to high contrast index waveguides
  - Multitude of optical building blocks – modulators, detectors, muxes, switches, etc
  - High Speed Modulation at extremely low power
  - CW laser source => low cost
- CMOS Compatibility
  - CMOS fabrication process => low cost
  - CMOS IC Simulation tools
  - CMOS IC layout tools
  - Monolithic integration of multiple opto-electronic building blocks in simulation tools => Large scale integration

CMOS Photonics enables a new class of low power, low cost, high density solutions

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